

PMEG2005BELD

20 V, 0.5 A low VF MEGA Schottky barrier rectifier

4 July 2012

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD882D (DFN1006D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage $V_F \leq 390$ mV
- AEC-Q101 qualified
- Ultra small and leadless SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; $T_{sp} \leq 140$ °C; square wave	-	-	0.5	A
		$\delta = 0.5$; $f = 20$ kHz; $T_{amb} \leq 115$ °C; square wave	[1]	-	0.5	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	20	V
V_F	forward voltage	$I_F = 500$ mA; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C	-	353	390	mV

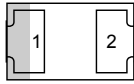



Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_R	reverse current	$V_R = 10\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	28	50	μA

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 <p>Transparent top view</p> <p>DFN1006D-2 (SOD882D)</p>	 <p>sym001</p>
2	A	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

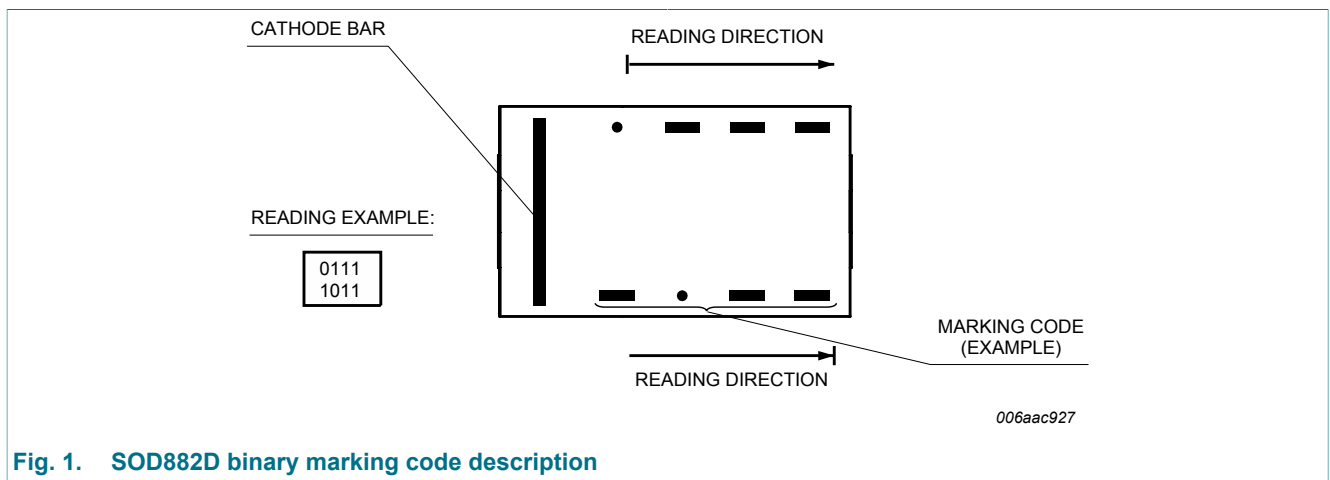
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2005BELD	DFN1006D-2	Leadless ultra small plastic package; 2 terminals	SOD882D

4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2005BELD	0010 1000



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	20	V
I_F	forward current	$T_{sp} \leq 140\text{ °C}$		-	0.5	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{sp} \leq 140\text{ °C}$; square wave		-	0.5	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{amb} \leq 115\text{ °C}$; square wave	[1]	-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$		-	3	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; $T_{j(init)} = 25\text{ °C}$; square wave		-	6	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2][3]	-	370	mW
			[1][3]	-	735	mW
			[4][3]	-	1135	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2][3]	-	-	340	K/W
			[1][4][3]	-	-	170	K/W
			[1][5][3]	-	-	110	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	25	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

[6] Soldering point of cathode tab.

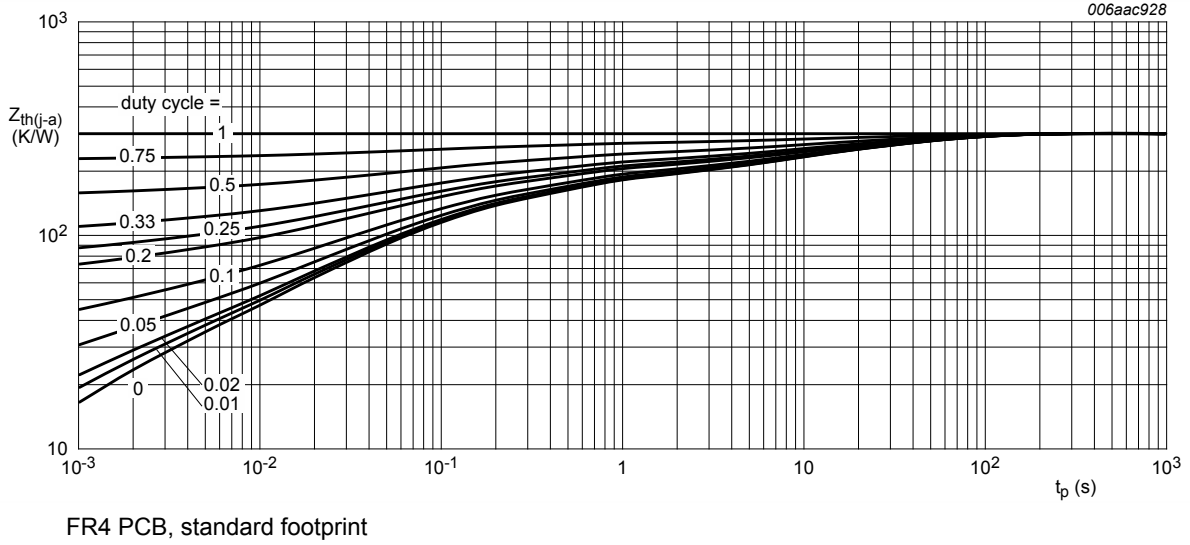


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

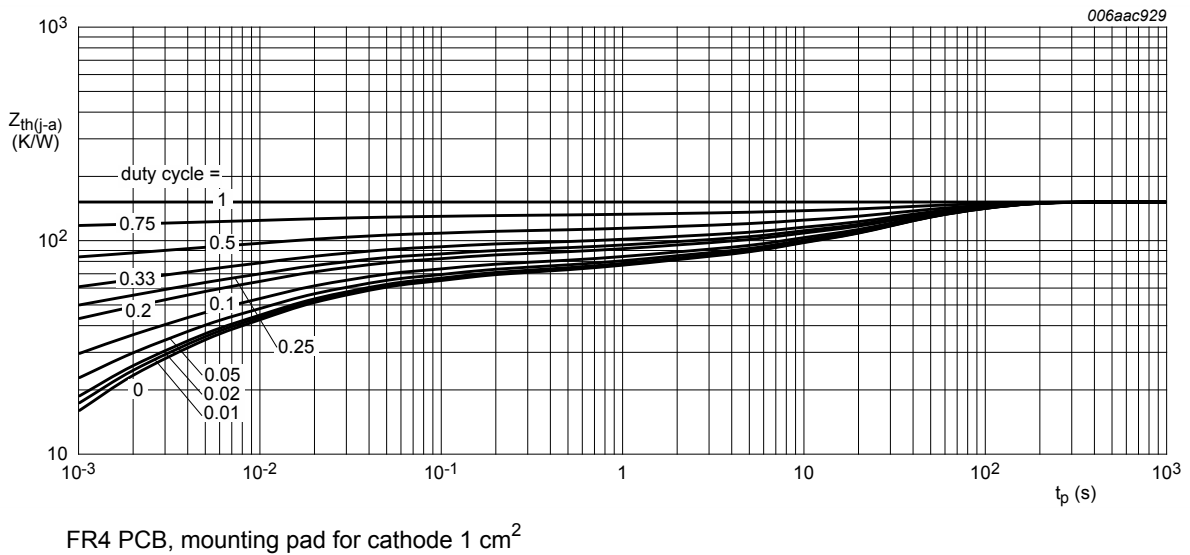
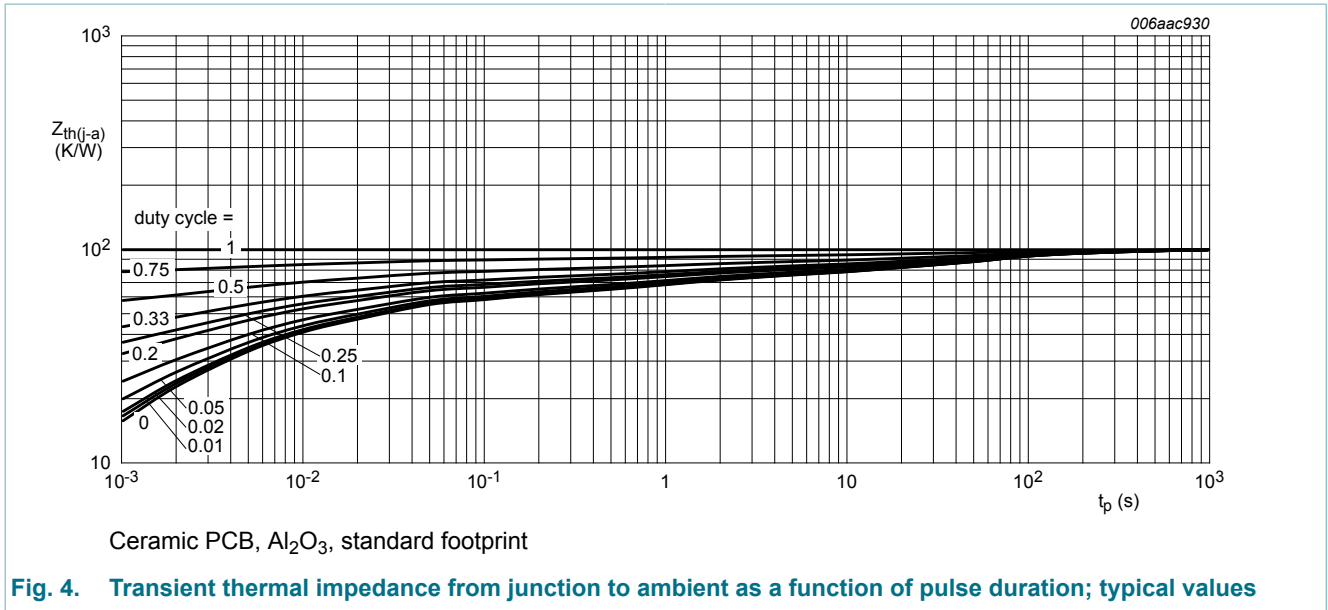


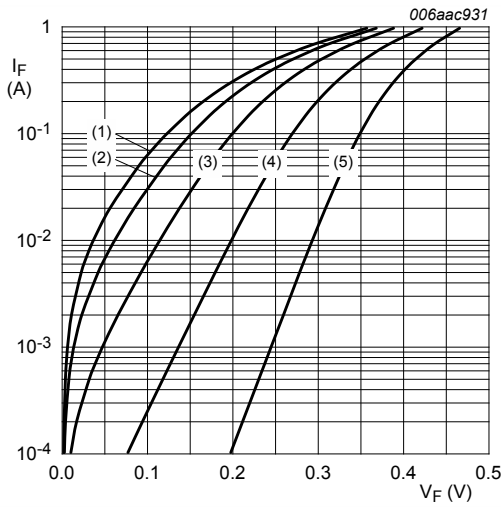
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



7. Characteristics

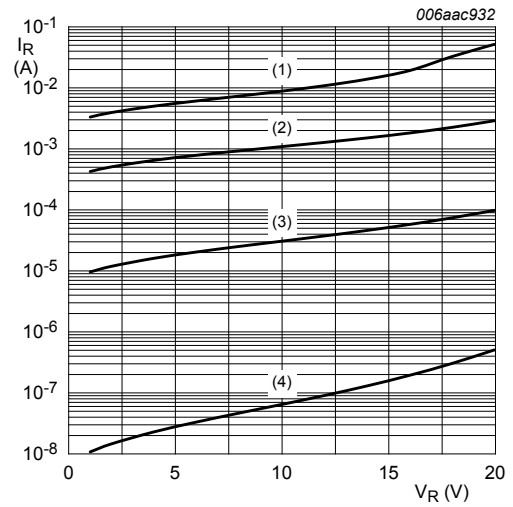
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 0.1 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02 ; T _j = 25 °C	-	79	105	mV
		I _F = 1 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02 ; T _j = 25 °C	-	137	170	mV
		I _F = 10 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02 ; T _j = 25 °C	-	197	235	mV
		I _F = 100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02 ; T _j = 25 °C	-	266	310	mV
		I _F = 500 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02 ; T _j = 25 °C	-	353	390	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	-	28	50	μA
		V _R = 20 V; T _j = 25 °C	-	87	200	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	31	40	pF
t _{rr}	reverse recovery time	I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C	-	1.6	-	ns
V _{FRM}	peak forward recovery voltage	I _F = 0.5 A; dI _F /dt = 20 A/μs; T _j = 25 °C	-	565	-	mV



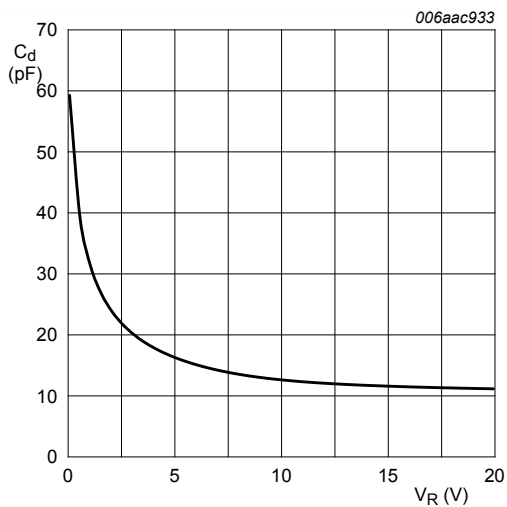
- (1) $T_j = 150^\circ\text{C}$
- (2) $T_j = 125^\circ\text{C}$
- (3) $T_j = 85^\circ\text{C}$
- (4) $T_j = 25^\circ\text{C}$
- (5) $T_j = -40^\circ\text{C}$

Fig. 5. Forward current as a function of forward voltage; typical values



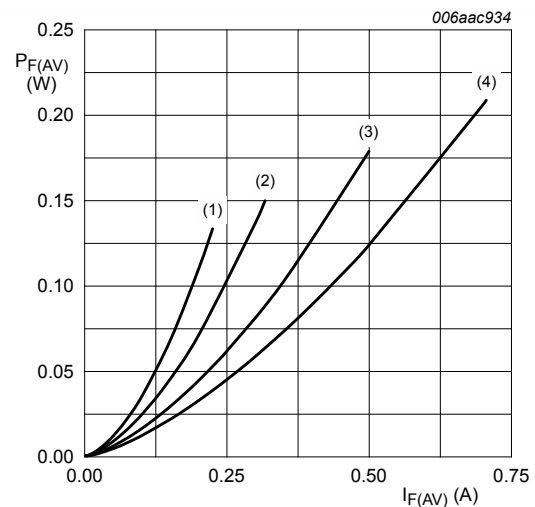
- (1) $T_j = 125^\circ\text{C}$
- (2) $T_j = 85^\circ\text{C}$
- (3) $T_j = 25^\circ\text{C}$
- (4) $T_j = -40^\circ\text{C}$

Fig. 6. Reverse current as a function of reverse voltage; typical values



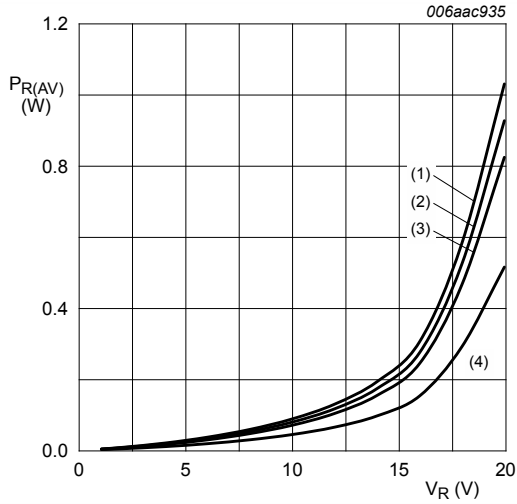
$f = 1\text{ MHz}; T_{\text{amb}} = 25^\circ\text{C}$

Fig. 7. Diode capacitance as a function of reverse voltage; typical values



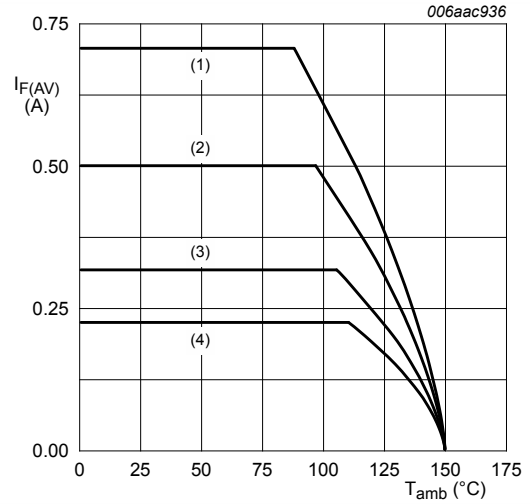
- $T_j = 150^\circ\text{C}$
- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

Fig. 8. Average forward power dissipation as a function of average forward current; typical values



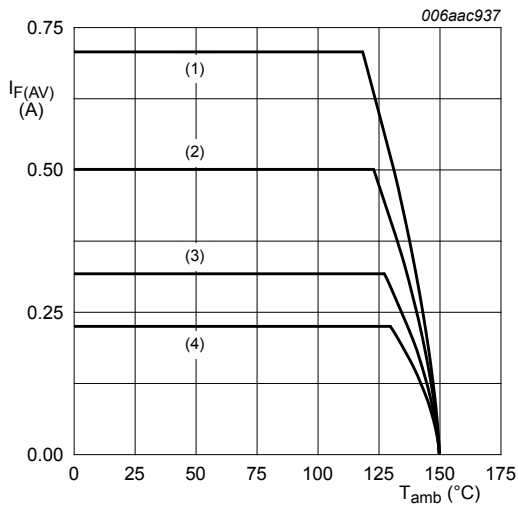
$T_j = 125\text{ }^\circ\text{C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.9$; $f = 20\text{ kHz}$
 (3) $\delta = 0.8$; $f = 20\text{ kHz}$
 (4) $\delta = 0.5$; $f = 20\text{ kHz}$

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



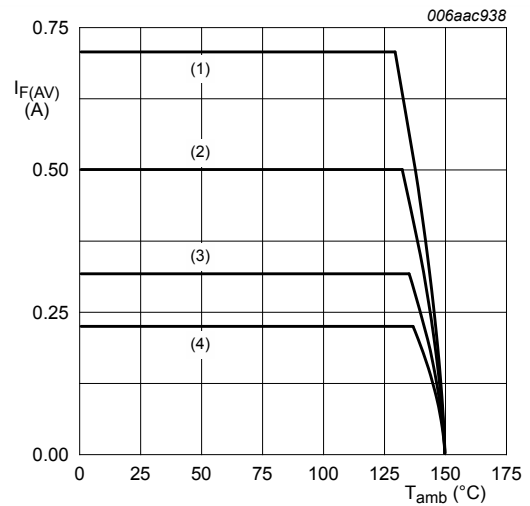
FR4 PCB, standard footprint
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$
 (2) $\delta = 0.5$
 (3) $\delta = 0.2$
 (4) $\delta = 0.1$

Fig. 10. Average forward current as a function of ambient temperature; typical values



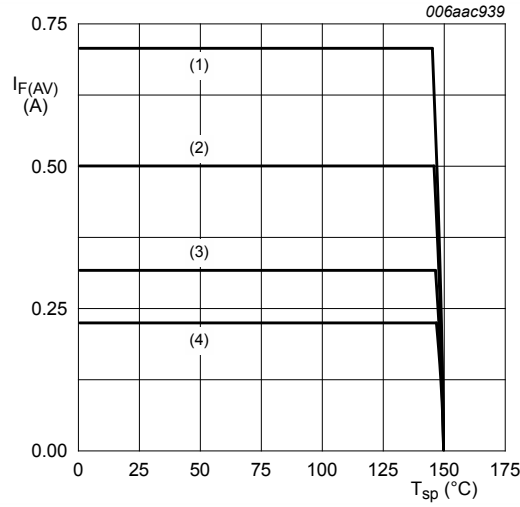
FR4 PCB, mounting pad for cathode 1 cm^2
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$
 (2) $\delta = 0.5$
 (3) $\delta = 0.2$
 (4) $\delta = 0.1$

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3 , standard footprint
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$
 (2) $\delta = 0.5$
 (3) $\delta = 0.2$
 (4) $\delta = 0.1$

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$

- (1) $\delta = 1$
- (2) $\delta = 0.5$
- (3) $\delta = 0.2$
- (4) $\delta = 0.1$

Fig. 13. Average forward current as a function of solder point temperature; typical values

8. Test information

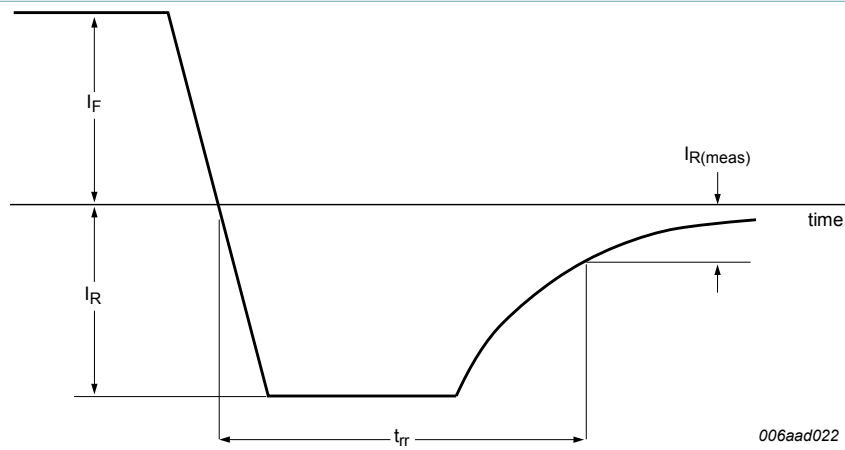


Fig. 14. Reverse recovery definition

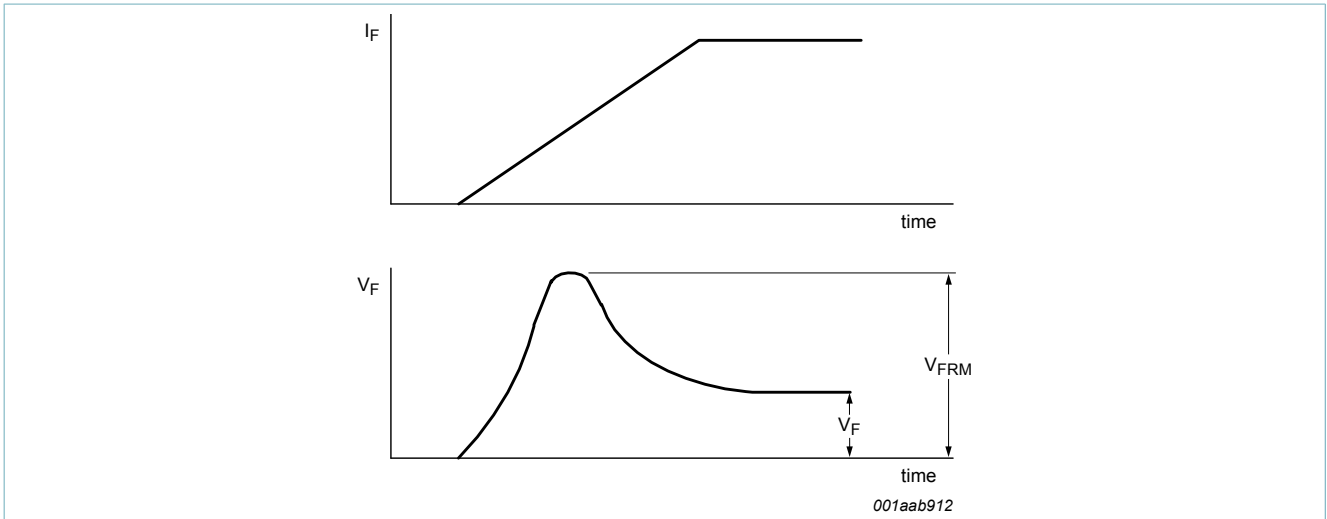


Fig. 15. Forward recovery definition

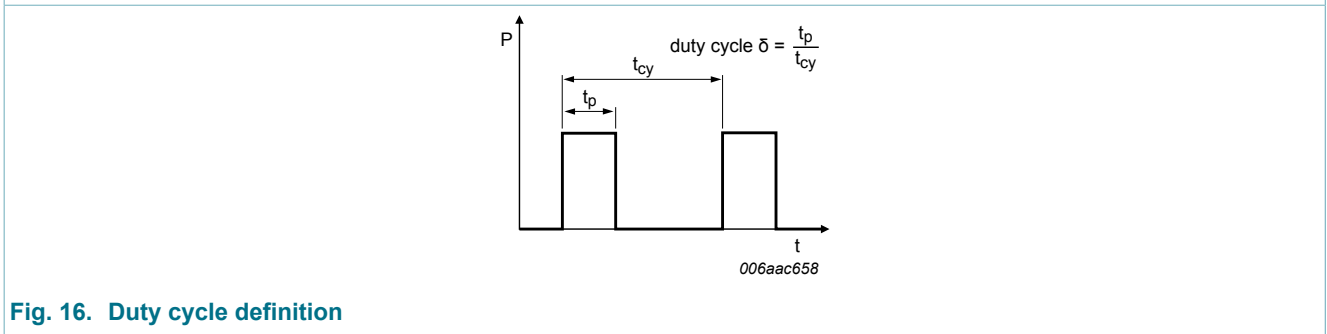


Fig. 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

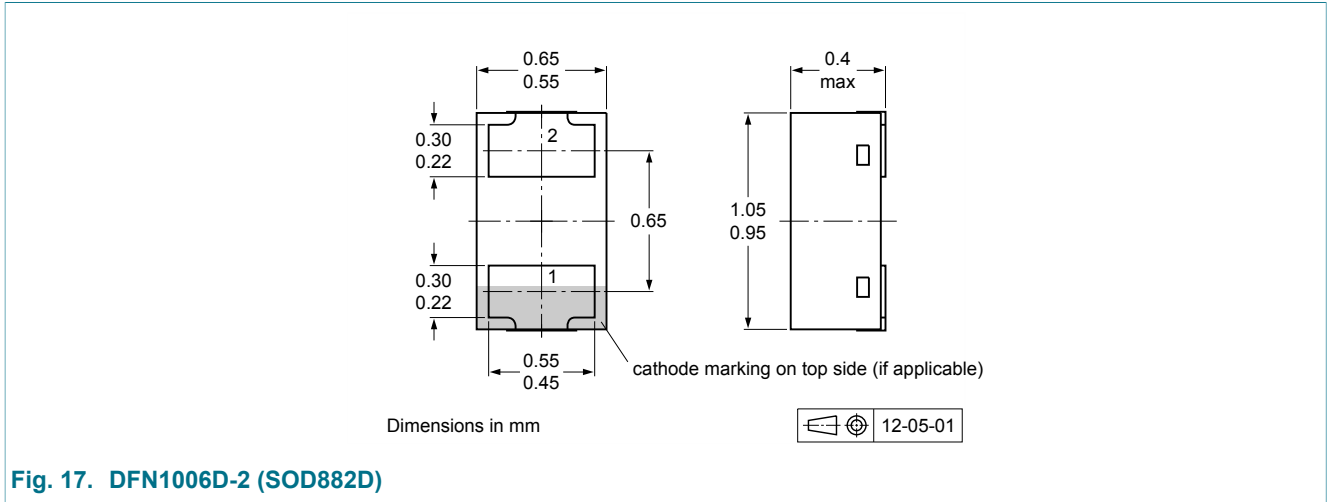


Fig. 17. DFN1006D-2 (SOD882D)

10. Soldering

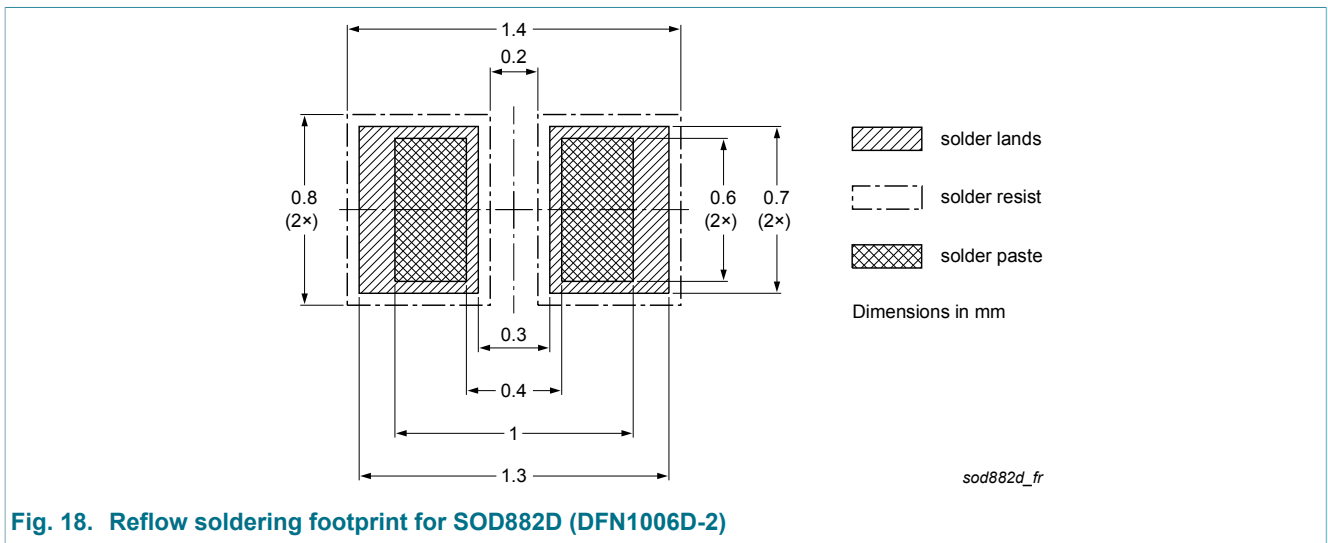


Fig. 18. Reflow soldering footprint for SOD882D (DFN1006D-2)

11. Revision history

Table 8. Revision history

Document ID	Release date	Document status	Change notice	Supersedes
PMEG2005BELD v.3	20120704	Product document	-	PMEG2005BELD v.2
Modifications:	<ul style="list-style-type: none"> Characteristics: V_{FRM} added; changed conditions of t_{rr}. 			
PMEG2005BELD v.2	20120312	Product document	-	PMEG2005BELD v.1
PMEG2005BELD v.1	20120111	Preliminary document	-	-

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
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